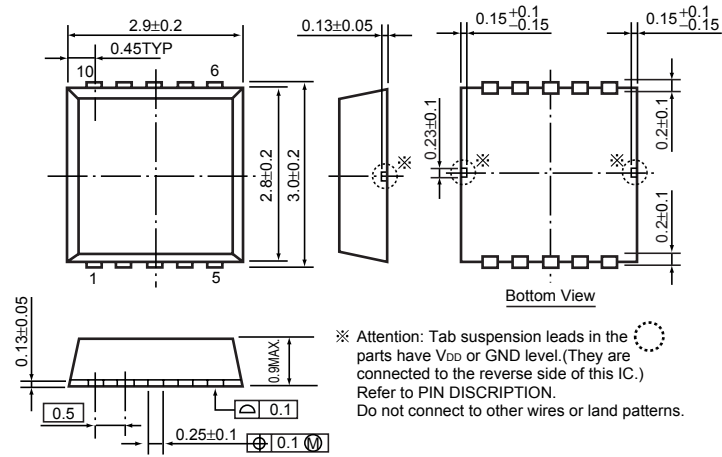


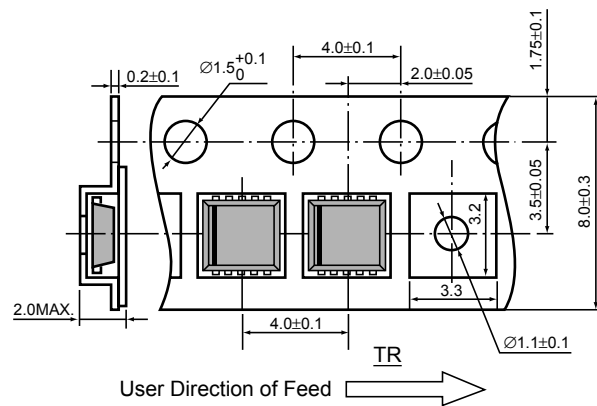
• SON-10

Unit: mm

PACKAGE DIMENSIONS

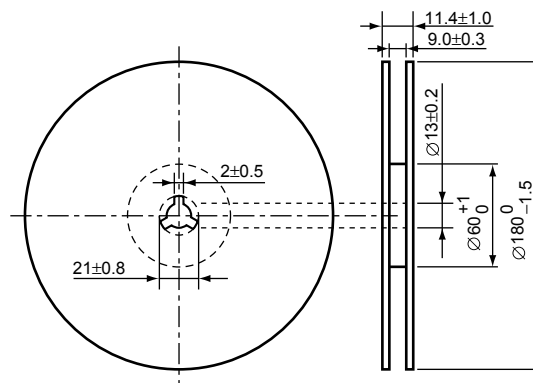


TAPING SPECIFICATION



TAPING REEL DIMENSIONS

(1reel=3000pcs)



## POWER DISSIPATION (SON-10)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

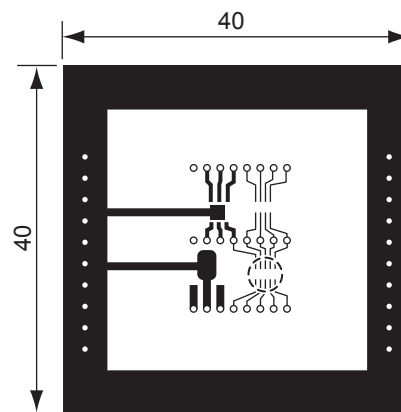
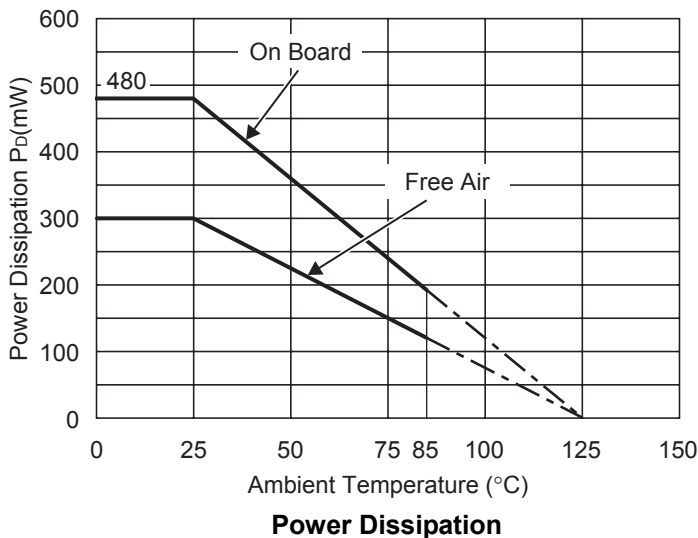
### Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plactic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

### Measurement Result

( $T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$ )

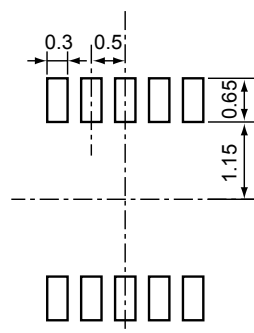
	Standard Land Pattern	Free Air
Power Dissipation	480mW	300mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.48W=208^{\circ}C/W$	333 $^{\circ}C/W$



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

## RECOMMENDED LAND PATTERN



(Unit: mm)